



(1<sup>st</sup> Quarter)

(2<sup>nd</sup> Quarter)

(3<sup>rd</sup> Quarter)

(4<sup>th</sup> Quarter)

JANUARY

WK	sun	mon	tue	wed	thu	fri	sat
1				1	2	3	4
2	5	6	7	8	9	10	11
3	12	13	14	15	16	17	18
4	19	20	21	22	23	24	25

APRIL

WK	sun	mon	tue	wed	thu	fri	sat
14	30	31	1	2	3	4	5
15	6	7	8	9	10	11	12
16	13	14	15	16	17	18	19
17	20	21	22	23	24	25	26

JULY

WK	sun	mon	tue	wed	thu	fri	sat
27	29	30	1	2	3	4	5
28	6	7	8	9	10	11	12
29	13	14	15	16	17	18	19
30	20	21	22	23	24	25	26

OCTOBER

WK	sun	mon	tue	wed	thu	fri	sat
40	28	29	30	1	2	3	4
41	5	6	7	8	9	10	11
42	12	13	14	15	16	17	18
43	19	20	21	22	23	24	25

FEBRUARY

WK	sun	mon	tue	wed	thu	fri	sat
5	26	27	28	29	30	31	1
6	2	3	4	5	6	7	8
7	9	10	11	12	13	14	15
8	16	17	18	19	20	21	22

MAY

WK	sun	mon	tue	wed	thu	fri	sat
18	27	28	29	30	1	2	3
19	4	5	6	7	8	9	10
20	11	12	13	14	15	16	17
21	18	19	20	21	22	23	24

AUGUST

WK	sun	mon	tue	wed	thu	fri	sat
31	27	28	29	30	31	1	2
32	3	4	5	6	7	8	9
33	10	11	12	13	14	15	16
34	17	18	19	20	21	22	23

NOVEMBER

WK	sun	mon	tue	wed	thu	fri	Sat
44	26	27	28	29	30	31	1
45	2	3	4	5	6	7	8
46	9	10	11	12	13	14	15
47	16	17	18	19	20	21	22

MARCH

WK	sun	mon	tue	wed	thu	fri	sat
9	23	24	25	26	27	28	1
10	2	3	4	5	6	7	8
11	9	10	11	12	13	14	15
12	16	17	18	19	20	21	22
13	23	24	25	26	27	28	29

JUNE

WK	sun	mon	tue	wed	thu	fri	sat
22	25	26	27	28	29	30	31
23	1	2	3	4	5	6	7
24	8	9	10	11	12	13	14
25	15	16	17	18	19	20	21
26	22	23	24	25	26	27	28

SEPTEMBER

WK	sun	mon	tue	wed	thu	fri	sat
35	24	25	26	27	28	29	30
36	31	1	2	3	4	5	6
37	7	8	9	10	11	12	13
38	14	15	16	17	18	19	20
39	21	22	23	24	25	26	27

DECEMBER

WK	sun	mon	tue	wed	thu	fri	Sat
48	23	24	25	26	27	28	29
49	30	1	2	3	4	5	6
50	7	8	9	10	11	12	13
51	14	15	16	17	18	19	20
52	21	22	23	24	25	26	27
	28	29	30	31			

• IPOH, MALAYSIA PUBLIC HOLIDAYS:-

1	Jan	New Year's Day
29 & 30	Jan	Chinese New Year
11	Feb	Thaipusam
31 & 1	Mar/Apr	Hari Raya Puasa
1	May	Labor Day
2	Jun	Agung's Birthday
7	Jun	Hari Raya Haji

27	Jun	Awal Muharram
31 & 1	Aug/Sept	National Day (Substitute)
16	Sep	Malaysia Day
20	Oct	Deepavali
7	Nov	Perak Sultan's Birthday
25	Dec	Christmas Day

• CHENGDU, CHINA PUBLIC HOLIDAYS:-

1	Jan	New Year's Day
28, 29 & 30	Jan	Chinese New Year
5	Apr	Ching Ming Festival
1	May	Labor Day

31	May	Dragon Boat Festival
1, 2 & 3	Oct	China National Holidays
6	Oct	Mid-Autumn Festival

• UNITED KINGDOM PUBLIC HOLIDAYS:-

1	Jan	New Year's Day
18	Apr	Good Friday
21	Apr	Easter Monday
5	May	May Bank Holiday

26	May	Spring Bank Holidays
25	Aug	Summer Bank Holidays
25	Dec	Christmas Day
26	Dec	Boxing Day

• U.S.A. PUBLIC HOLIDAYS:-

1	Jan	New Year's Day
26	May	Memorial Day
4	Jul	Independence Day

1	Sep	Labor Day
27	Nov	Thanksgiving Day
25	Dec	Christmas Day

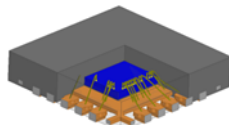


Leadless		Leaded		Array		Wafer Bump + DPS			
Packages	Total Thickness	Packages	Lead Count	Packages	Lead Count	With Land Pattern	With Ball I/O	Wafer Bumping Options	Backend Assembly
SLP <sup>1,2,3,4,5,6</sup>	0.25 – 0.90	SOIC-N <sup>1,2,3,4,5</sup> ( 150mils )	8, 16	SOT23 <sup>1,2,5</sup>	3, 5, 6	LGA <sup>1,2,3,4,7,8</sup>	BGA <sup>1,2,3,7</sup>	Ball Drop	WLCSP / DPS <sup>9</sup>
Module SLP <sup>1,2,3,4,6,7</sup>	0.90 – 4.00	QSOP <sup>1,5</sup> ( 150mils )	16	TSOT <sup>1,2</sup>	5, 6, 8	<div style="border: 1px solid black; padding: 5px; display: inline-block;"> <b>MEMS</b> </div>		Cu Pillar Bump	Flip Chip
MIS <sup>1,2,3,4,5,6,7,8</sup>	0.33 – 0.80	TSSOP <sup>1,3,4</sup> ( 4.4mm )	14, 16, 20, 24, 28	SC70 <sup>1</sup>	3, 4, 5, 6			<div style="border: 1px solid black; padding: 5px; display: inline-block;"> Laminate Substrate      Cu Lead Frame </div>	
		MSOP <sup>1,4</sup> ( 3.0mm )	8, 10	SOT563 <sup>2</sup>	6	LGA <sup>1,2,3,4,7,10,11,12</sup>	SLP <sup>1,2,3,4,5,7,12</sup>		
				SOT583 <sup>2</sup>	8				

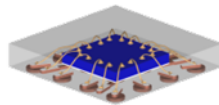
  

**Legend**

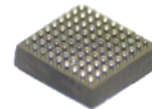
1 – Wire Bond Interconnect	2 – Flip Chip Interconnect	3 – Stacked Die
4 – Thermally Enhanced (exposed paddle)	5 – Chip on Leads	6 – Wettable Flanks ( automotive )
7 – System in Package ( passive integration )	8 – Electromagnetic Interference Shielding	9 – Back Side Protection
10 – Metal Lid Attach	11 – LCP Lid Attach	12 – Customized Molding



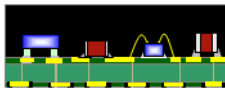
[SLP](#)



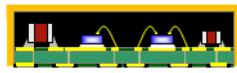
[MIS](#)



[WLCSP / WLBGA](#)  
With & Without BSP



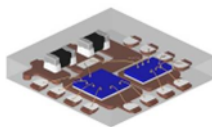
[Combo WB + FC version SiP](#)



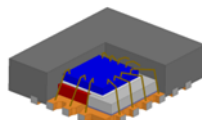
[Module LGA with EMI Shield](#)  
Sputtered Ti-Cu-Ti



[Module MIS with EMI Shield](#)  
Conformal Shielding



[Module SLP](#)



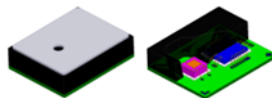
[Stacked Module SLP](#)



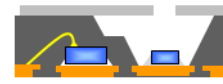
[Metal Lid Module LGA](#)



[LGA-FL \( Top Port \)](#)



[LGA-MC](#)



[SLP-MC \( Side by Side \)](#)

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